

**Amendments to the Claims**

This listing of claims will replace all prior versions and listings of claims in the application.

**Listing of Claims**

1. (Currently Amended) A system, comprising:

a chamber configured to process one or more wafers for the fabrication of microelectronic devices;

a plurality of reservoirs serially coupled to the chamber via a plurality of intervening pipes, wherein the system is adapted to transport a process fluid used to process-treat the wafers from the plurality of reservoirs to a fluid inlet of the chamber, and wherein the fluid inlet is configured to dispense the process fluid on the one or more wafers;

one or more devices adapted to maintain the process fluid supplied to the chamber within a first temperature range; and

one or more additional devices adapted to maintain the process fluid residing in a first set of the plurality of reservoirs within a second temperature range distinct from the first temperature range, wherein a second set of the plurality of reservoirs are used to maintain the process fluid residing therein within a third temperature range distinct from the first and second temperature ranges.

2. (Original) The system of claim 1, wherein the chamber is configured to conduct an electroless deposition process.

3. (Currently Amended) The system of claim 1, wherein the system is further adapted to transport the process fluid from the chamber to one or more of the plurality of reservoirs.

4. (Currently Amended) The system of claim 1, wherein the system is further adapted to circulate the process fluid between at least two of the plurality of reservoirs.

5. (Original) The system of claim 1, wherein the first temperature range is higher than the second temperature range.
6. (Original) The system of claim 1, wherein the second temperature range is higher than the third temperature range.
7. (Original) The system of claim 1, wherein the first temperature range is lower than the second temperature range, and wherein the second temperature range is lower than the third temperature range.
8. (Currently Amended) The system of claim 1, wherein the ~~first~~third temperature range comprises temperatures between approximately 42° C and approximately 50° C.
9. (Currently Amended) The system of claim 1, wherein the second temperature range comprises temperatures between approximately ~~70~~50° C and approximately ~~95~~70° C.
10. (Currently Amended) The system of claim 1, wherein the ~~third~~first temperature range comprises temperatures between approximately ~~95~~70° C and approximately 110° C.
11. (Currently Amended) The system of claim 1, further comprising one or more different devices adapted to maintain the ~~process~~ fluid residing in the second set of the plurality of reservoirs within the third temperature range.
12. (Original) The system of claim 1, further comprising one or more additional process chambers coupled to at least one of the plurality of reservoirs.

13. (Currently Amended) A system, comprising:

a chamber configured to process one or more wafers for the fabrication of microelectronic devices;

a plurality of tanks serially coupled to the chamber and adapted to store a process fluid used to process-treat the wafers, wherein the chamber comprises a fluid inlet configured to;

receive the process fluid from at least one of the plurality of tanks; and

supply the process fluid to the one or more wafers; and

a plurality of temperature controllers positioned within the system such that the chamber and the plurality of tanks are characterized into at least three different zones based upon adaptations of the temperature controllers to maintain the process fluid within distinct temperature ranges in the respective zones while processing the wafers.

14. (Original) The system of claim 13, wherein the plurality of temperature controllers are positioned such that the at least three different zones are arranged in ascending order based upon their respective temperature ranges, and wherein the zone comprising the chamber has the highest temperature range.

15. (Original) The system of claim 13, wherein the plurality of temperature controllers are positioned such that the at least three different zones are arranged in descending order based upon their respective temperature ranges, and wherein the zone comprising the chamber has the lowest temperature range.

16. (Original) The system of claim 13, wherein one of the plurality of temperature controllers is arranged within the chamber.

17. (Currently Amended) The system of claim 13, wherein one of the plurality of temperature controllers is coupled to a fluid inlet of the chamber.

18. (Currently Amended) The system of claim 13, wherein one of the plurality of temperature controllers is coupled to one of a plurality of pipes configured to transport the process fluid from the plurality of tanks to the chamber.

19. (Original) The system of claim 13, wherein one of the plurality of temperature controllers is arranged within one of the plurality of tanks.

20. (Original) The system of claim 13, wherein at least one of the plurality of temperature controllers comprises an infrared heater.

21. -- 24. (Canceled)